OptiMOS™2 Power-Transistor

Features

- Fast switching MOSFET for SMPS
- Optimized technology for notebook DC/DC
- Qualified according to JEDEC[1] for target applications

Thermal resistance, junction - soldering point

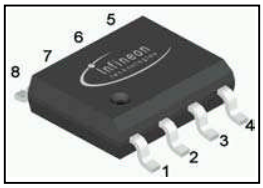
Thermal resistance, junction - ambient

- Excellent gate charge x $R_{DS(on)}$ product (FOM)
- Very low on-resistance $R_{DS(on)}$
- Avalanche rated
- dv/dt rated
- Pb-free plating; RoHS compliant
- Halogen-free according to IEC61249-2-21

Product Summary

V_{DS}	30	V
$R_{DS(on),max}$	20	mΩ
I_D	7.9	A

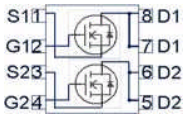
P-DSO-8



RoHS

Halogen-Free

Type	Package	Marking
BSO200N03	PG-DSO-8	200N3



Maximum ratings, at T_j=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value		Unit
			10 secs	steady state	
Continuous drain current	I_D	T_A=25 °C[2]	7.9	6.6	A
		T_A=70 °C[2]	6.3	5.3	
Pulsed drain current	$I_{D,pulse}$	T_A=25 °C[3]	32		
Avalanche energy, single pulse	E_{AS}	I_D=7.9 A, R_{GS}=25 Ω	27		mJ
Reverse diode dv/dt	dv/dt	I_D=7.9 A, V_{DS}=20 V, di/dt=200 A/µs, $T_{j,max}$=150 °C	6		kV/µs
Gate source voltage	V_{GS}		±20		V
Power dissipation	P_{tot}	T_A=25 °C[2]	2.0	1.4	W
Operating and storage temperature	T_j, T_{stg}		-55 ... 150		°C
IEC climatic category; DIN IEC 68-1			55/150/56		

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics						
Thermal resistance, junction - soldering point	R_{thJS}		-	-	50	K/W
Thermal resistance, junction - ambient	R_{thJA}	minimal footprint, t_p≤10 s	-	-	110	
		minimal footprint, steady state	-	-	150	
		6 cm^2 cooling area[2], t_p≤10 s	-	-	63	
		6 cm^2 cooling area[2], steady state	-	-	90	
Electrical characteristics, at T_j=25 °C, unless otherwise specified						
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS}=0 V, I_D=1 mA	30	-	-	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=13 µA	1.2	1.6	2	
Zero gate voltage drain current	I_{DSS}	V_{DS}=30 V, V_{GS}=0 V, T_j=25 °C	-	0.1	1	µA
		V_{DS}=30 V, V_{GS}=0 V, T_j=125 °C	-	10	100	
Gate-source leakage current	I_{GSS}	V_{GS}=20 V, V_{DS}=0 V	-	10	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=4.5 V, I_D=6.8 A	-	21.7	27	mΩ
		V_{GS}=10 V, I_D=7.9 A	-	16.7	20	
Gate resistance	R_G		-	1.5	-	Ω
Transconductance	g_{fs}	$\|V_{DS}\|>2\|I_D\|R_{DS(on)max}$, I_D=7.9 A	9	18	-	S

[1] J-STD20 and JESD22

[2] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm^2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

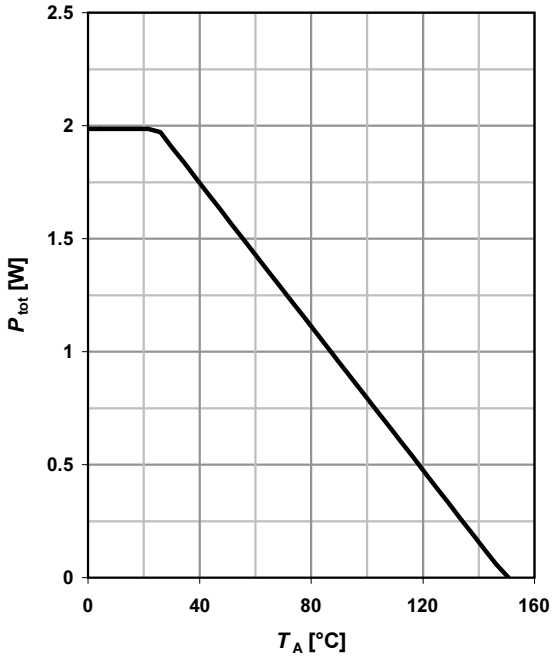
[3] See figure 3

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics						
Thermal resistance, ju	C_{iss}	V_{GS}=0 V, V_{DS}=15 V, f=1 MHz	-	756	1010	pF
Thermal resistance, j	C_{oss}		-	270	360	
Reverse transfer capacitance	C_{rss}		-	37	56	
Turn-on delay time	$t_{d(on)}$	V_{DD}=15 V, V_{GS}=10 V, I_D=3.9 A, R_G=2.7 Ω	-	3.9	5.8	ns
Rise time	t_r		-	3.2	4.8	
Turn-off delay time	$t_{d(off)}$		-	14	22	
Fall time	t_f		-	2.2	3.3	
Gate Charge Characteristics[4)]						
Gate to source charge	Q_{gs}	V_{DD}=15 V, I_D=3.9 A, V_{GS}=0 to 5 V	-	2.2	2.9	nC
Gate charge at threshold	$Q_{g(th)}$		-	1.2	1.6	
Gate to drain charge	Q_{gd}		-	1.5	2.3	
Switching charge	Q_{sw}		-	2.5	3.5	
Gate charge total	Q_g		-	6	8	
Gate plateau voltage	$V_{plateau}$		-	2.9	-	V
Gate charge total, sync. FET	$Q_{g(sync)}$	V_{DS}=0.1 V, V_{GS}=0 to 5 V	-	5.1	7	nC
Output charge	Q_{oss}	V_{DD}=15 V, V_{GS}=0 V	-	6	8	
Reverse Diode						
Diode continous forward current	I_S	T_A=25 °C	-	-	2	A
Diode pulse current	$I_{S,pulse}$		-	-	32	
Diode forward voltage	V_{SD}	V_{GS}=0 V, I_F=2 A, T_j=25 °C	-	0.77	1	V
Reverse recovery charge	Q_{rr}	V_R=12 V, I_F=I_S, di_F/dt =400 A/µs	-	-	8	nC

[4)] See figure 16 for gate charge parameter definition

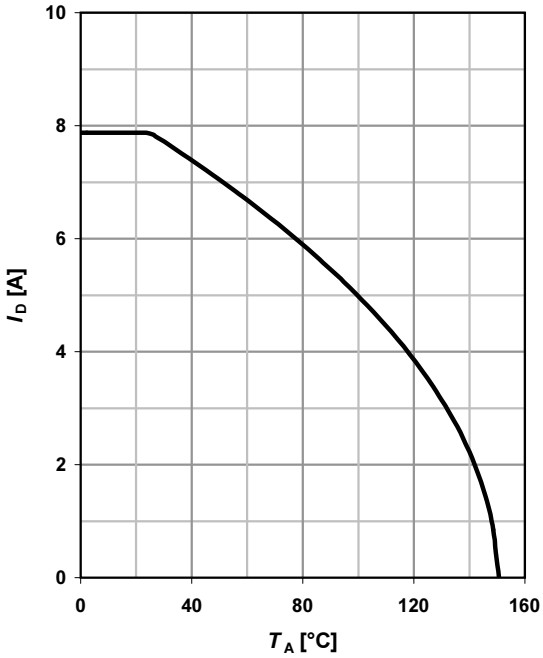
1 Power dissipation

P_{tot}=f(T_A); t_p≤10 s



2 Drain current

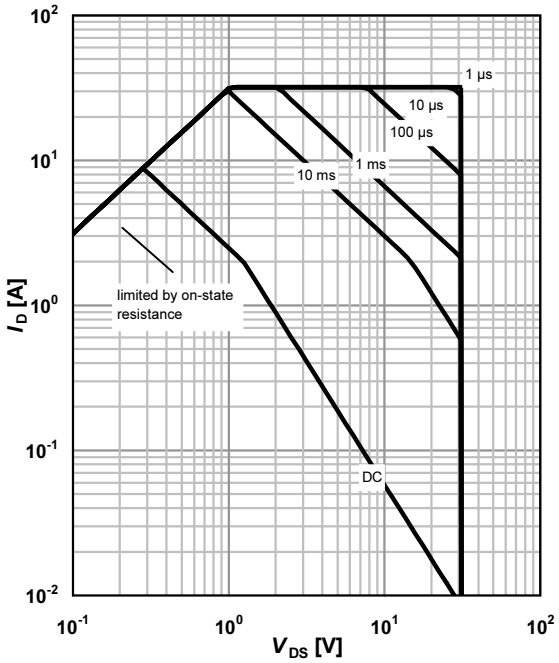
I_D=f(T_A); V_{GS}≥10 V; t_p≤10 s



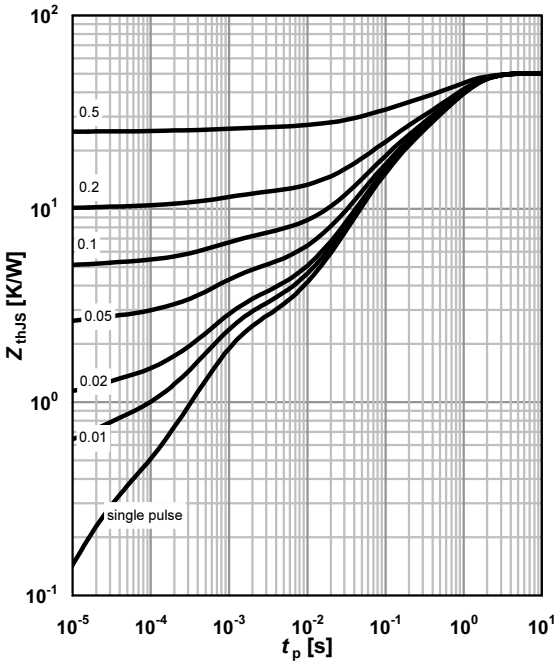
3 Safe operating area

Thermal resistance, junction - solderir Z_{thJS}=f(t_p)

Thermal resistance, junction - ambier parameter: $D=t_p/T$



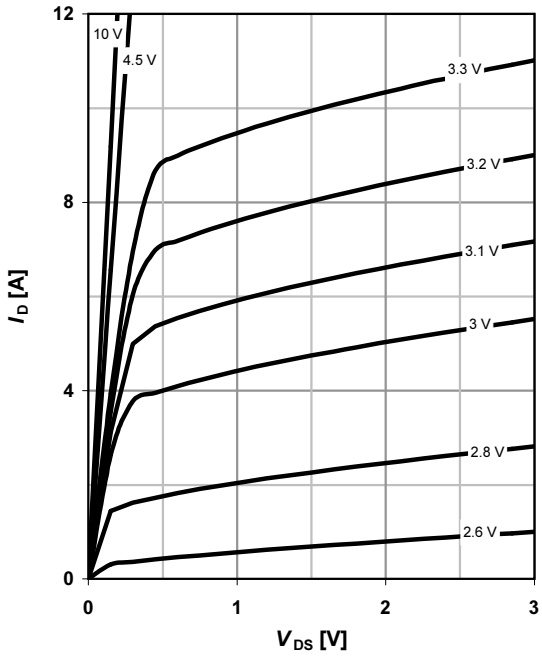
4 Max. transient thermal impedance



5 Typ. output characteristics

I_D=f(V_{DS}); T_j=25 °C

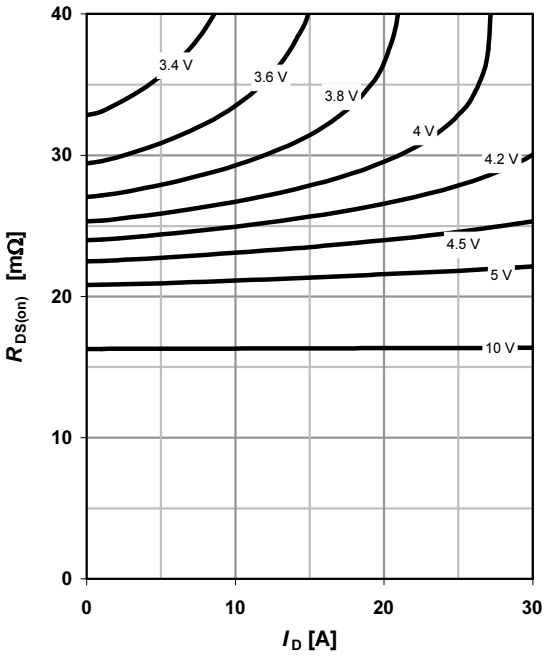
parameter: V_{GS}



6 Typ. drain-source on resistance

$R_{DS(on)}$=f(I_D); T_j=25 °C

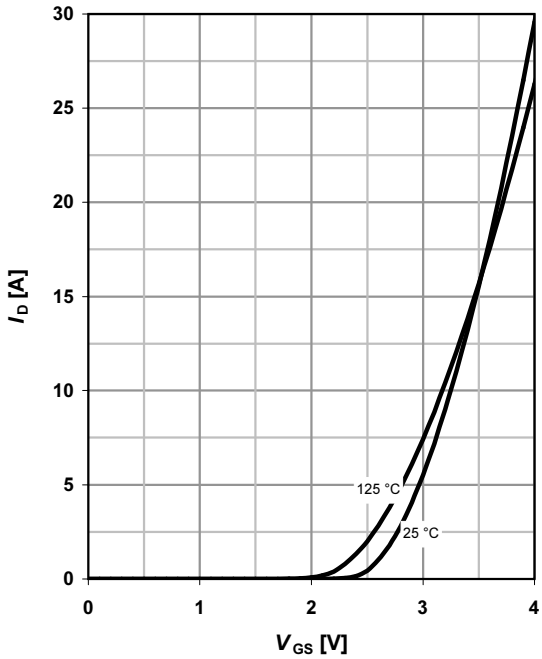
parameter: V_{GS}



7 Typ. transfer characteristics

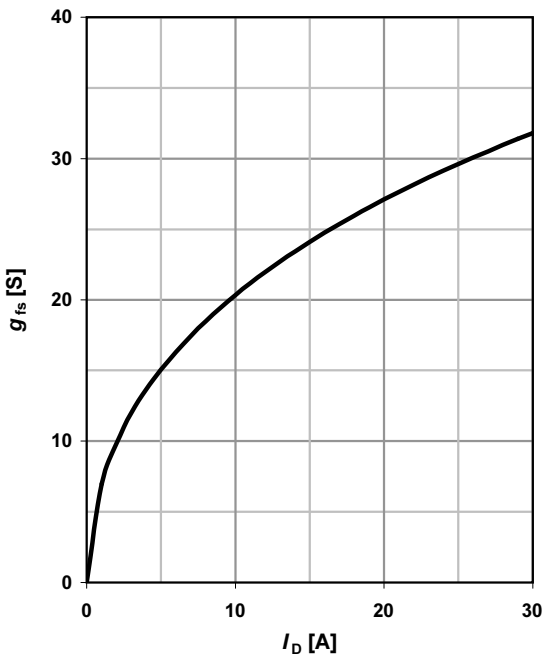
Thermal resistance, junction - solderir

Thermal resistance, junction - ambient



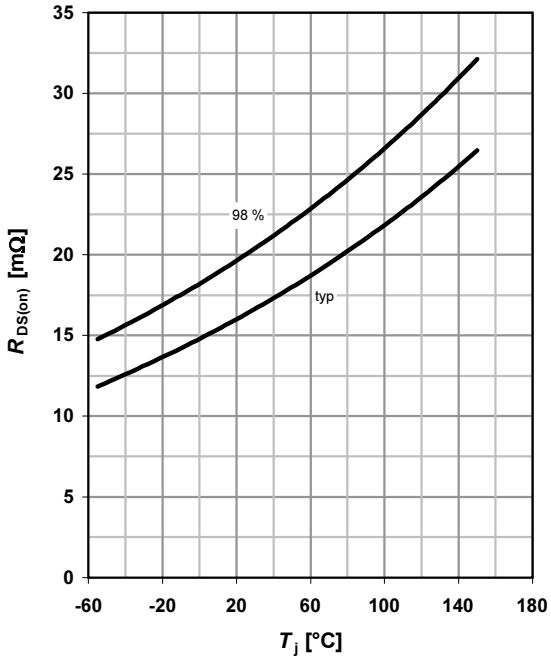
8 Typ. forward transconductance

g_{fs}=f(I_D); T_j=25 °C



9 Drain-source on-state resistance

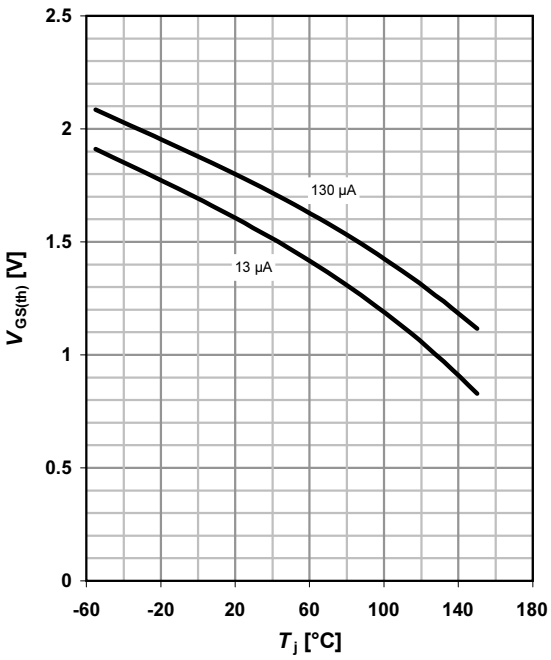
$R_{DS(on)}=f(T_j)$; $I_D=7.9$ A; $V_{GS}=10$ V



10 Typ. gate threshold voltage

$V_{GS(th)}=f(T_j)$; $V_{GS}=V_{DS}$

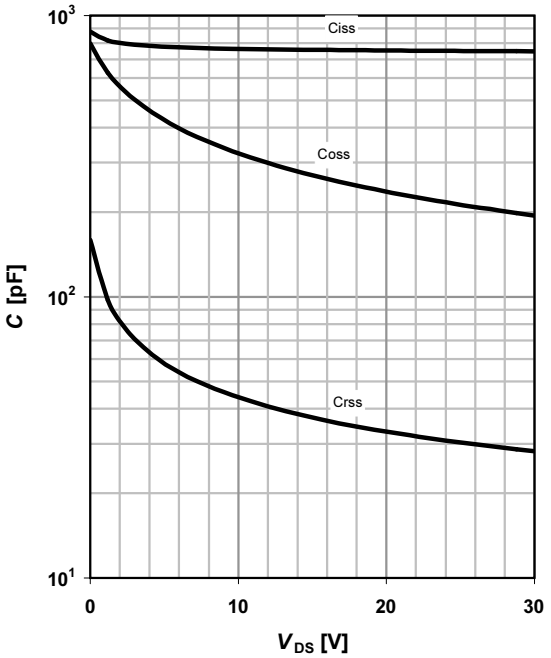
parameter: I_D



11 Typ. capacitances

Thermal resistance, junction - solderir

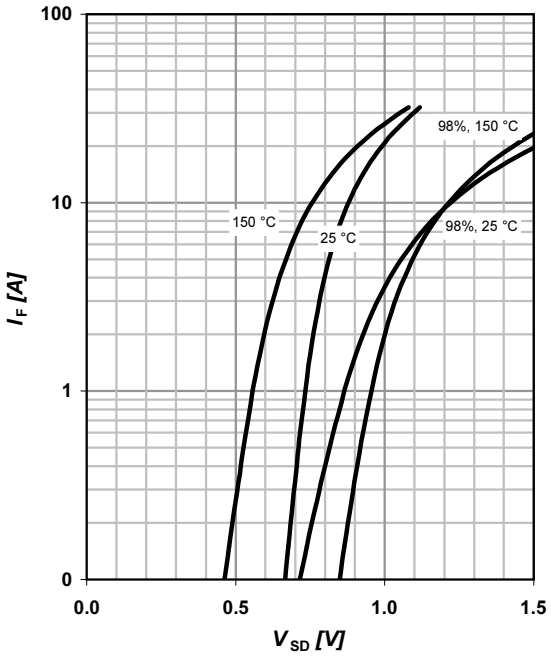
Thermal resistance, junction - ambier



12 Forward characteristics of reverse diode

$I_F=f(V_{SD})$

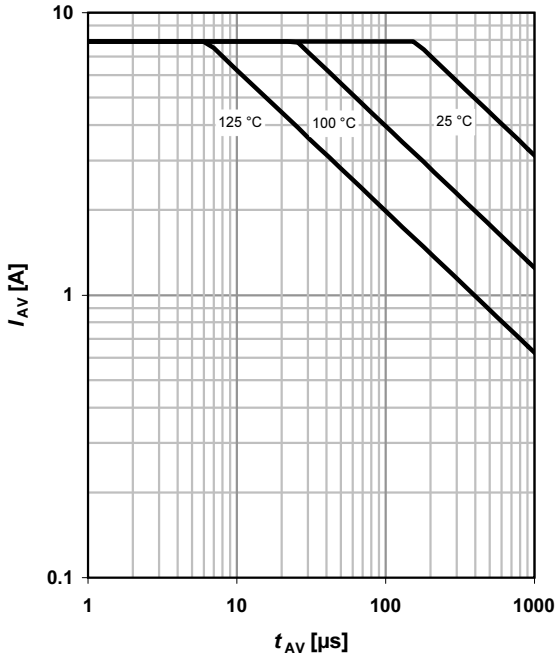
parameter: T_j



13 Avalanche characteristics

I_{AS}=f(t_{AV}); R_{GS}=25 Ω

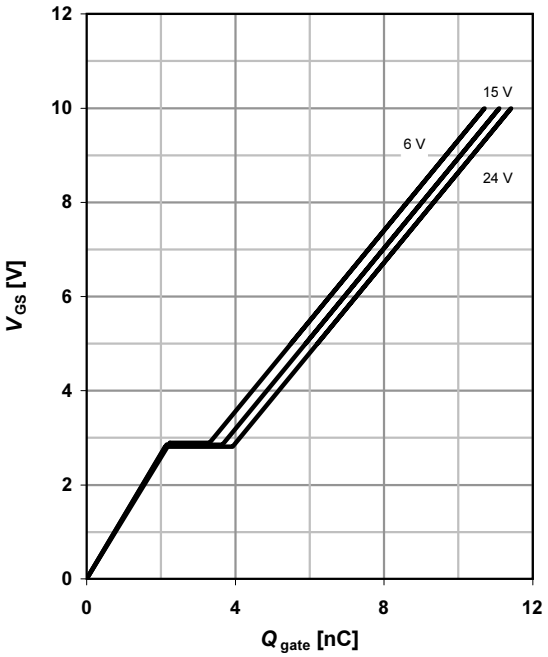
parameter: $T_{j(start)}$



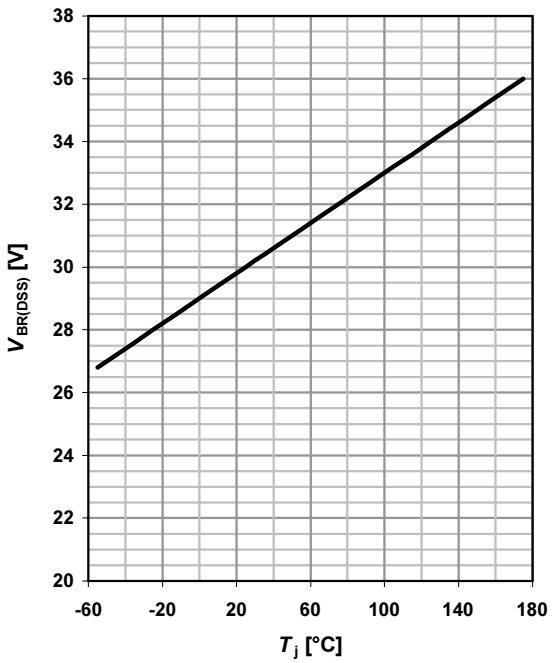
14 Typ. gate charge

V_{GS}=f(Q_{gate}); I_D=3.9 A pulsed

parameter: V_{DD}



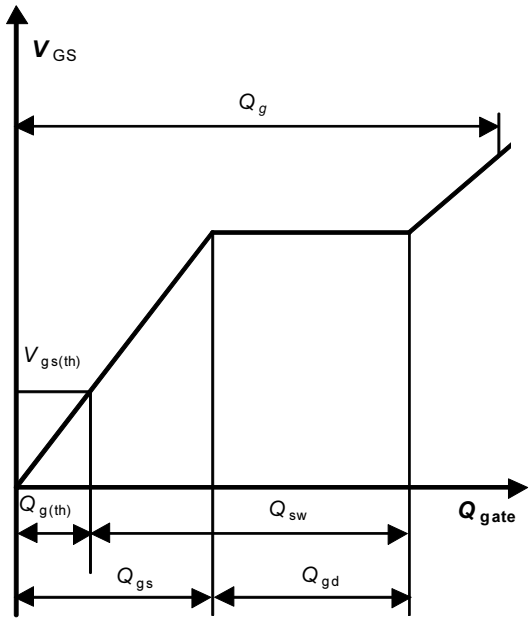
15 Drain-source breakdown voltage



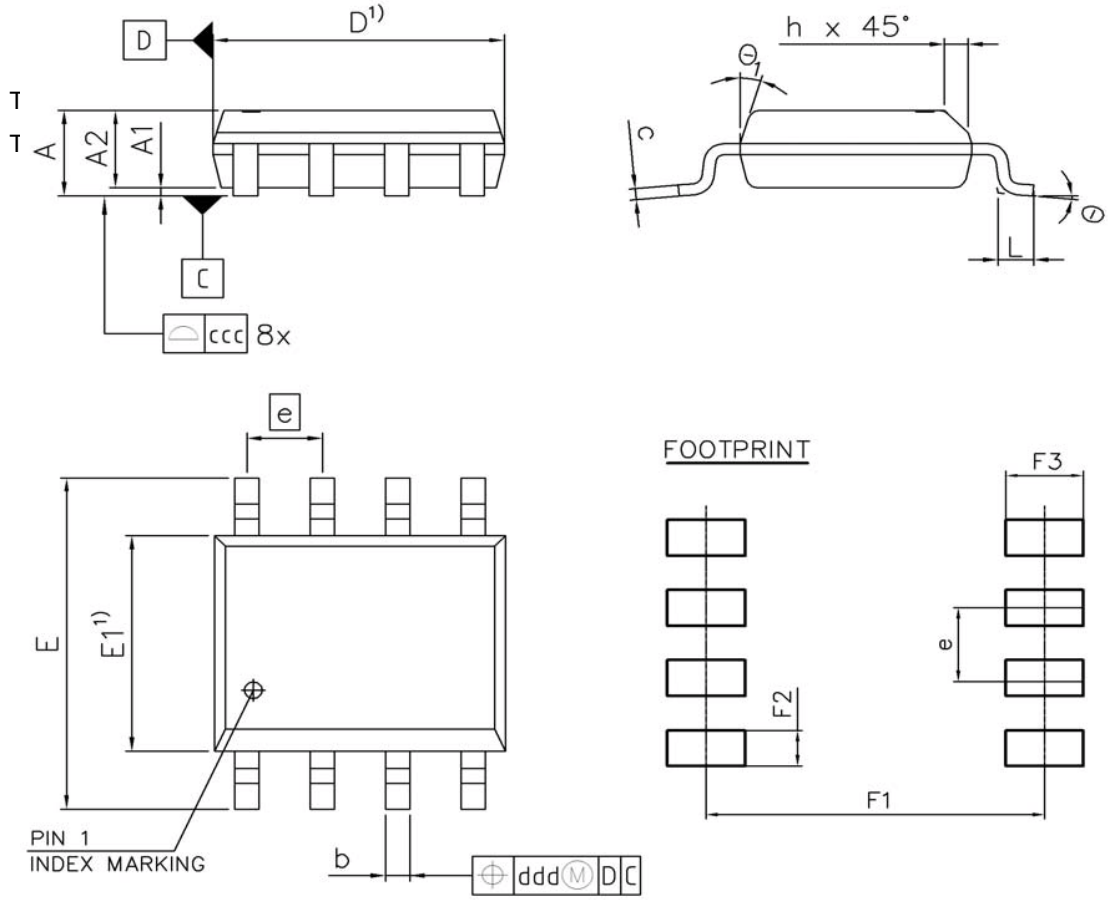
16 Gate charge waveforms

Thermal resistance, junction - soldering point

Thermal resistance, junction - ambient



Package Outline **PG-DSO-8**



1) DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	-	1.75	-	0.069
A1	0.10	-	0.004	-
A2	1.25	1.65	0.049	0.065
b	0.35	0.51	0.014	0.020
c	0.17	0.25	0.007	0.010
D	4.80	5.00	0.189	0.197
E	5.80	6.20	0.228	0.244
E1	3.80	4.00	0.150	0.157
e	1.27		0.050	
N	8		8	
L	0.39	0.89	0.015	0.035
h	0.23	0.50	0.009	0.020
Θ	0°	8°	0°	8°
Θ1	-	19°	-	19°
ccc	0.10		0.004	
ddd	0.25		0.010	
F1	5.59	5.79	0.220	0.228
F2	0.55	0.75	0.022	0.030
F3	1.21	1.41	0.048	0.056

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